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**AMENDMENTS TO THE CLAIMS**

The following listing of claims will replace all prior versions and listings of claims in the application.

**LISTING OF CLAIMS**

1. (currently amended) A cooling system for electronic equipment enclosures with densely packed components comprising:

an electronic equipment enclosure; a rack mounted within said enclosure;

a plurality of boards mounted to said rack, at least one of said boards having a plurality of heat generating components mounted thereon;

a plurality of microscale cooling assemblies each one of said cooling assemblies being connected to one of said plurality of heat generating components, each cooling assembly including a heat insulative housing, an inlet port formed in said housing for receiving a heat transferring fluid, an outlet port formed in said housing for passing said heat transferring fluid, a thermally conductive element connected to said housing, an evaporator chamber formed by said housing and said thermally conductive element upstream of said outlet port and a capillary passage formed in said housing between said inlet port and said evaporator chamber;

a first intake manifold mounted to said rack;

a first exhaust manifold mounted to said rack;

a second intake manifold mounted to said board and to said first intake manifold;

a second exhaust manifold mounted to said board and to said first exhaust manifold;

a first fluid conduit connecting said board mounted second intake manifold and each of said plurality of cooling assemblies;

a second fluid conduit connecting said board mounted ~~first exhaust~~ second exhaust manifold and each of said plurality of cooling assemblies;

a compressor;

a third fluid conduit connecting said rack mounted first intake manifold and said compressor; and

a fourth fluid conduit connecting said rack mounted first exhaust manifold and said compressor.

2. (original) The system of claim 1 wherein:

said rack includes a rail; and

said plurality of boards are mounted to said rail.

3. (original) The system of claim 1 including:

a backplane connected to said rack; and wherein

said plurality of boards are mounted to said backplane.

4. (original) The system of claim 1 including:

a backplane connected to said rack; and

said first intake manifold and said first exhaust manifold are connected to said backplane.

5. (original) The system of claim 1 including:

a backplane connected to said rack; and wherein

said rack includes a rail;

said first intake manifold and said first exhaust manifold are connected to said backplane; and

said plurality of boards are mounted to said rail and to said backplane.

6-14. (canceled)